

# Global Die Attach for Semiconductor Market Growth 2026-2032

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## Abstracts

The global Die Attach for Semiconductor market size is predicted to grow from US\$ 1943 million in 2025 to US\$ 3994 million in 2032; it is expected to grow at a CAGR of 9.5% from 2026 to 2032.

Die Attach is a core front-end process in advanced semiconductor packaging (especially in heterogeneous integration scenarios such as HBM and Chiplet). It refers to the process of precisely attaching bare dies (such as DRAM chips and logic chip cores in HBM) to the surface of a substrate, carrier wafer, or underlying stacked chips through physical bonding and mechanical fixation. It is a fundamental prerequisite for realizing electrical interconnection.

In 2024, the average price of Die Attach equipment was around US\$280,000 per unit, with sales of 7,093 units and an overall gross profit margin of around 40%.

United States market for Die Attach for Semiconductor is estimated to increase from US\$ million in 2025 to US\$ million by 2032, at a CAGR of % from 2026 through 2032.

China market for Die Attach for Semiconductor is estimated to increase from US\$ million in 2025 to US\$ million by 2032, at a CAGR of % from 2026 through 2032.

Europe market for Die Attach for Semiconductor is estimated to increase from US\$ million in 2025 to US\$ million by 2032, at a CAGR of % from 2026 through 2032.

Global key Die Attach for Semiconductor players cover HANMI Semiconductor, ASMPT, SEMES, Hanwha Semitech Co., Ltd, Yamaha Robotics (SHINKAWA), etc. In terms of revenue, the global two largest companies occupied for a share nearly % in 2025.

LP Information, Inc. (LPI) ' newest research report, the “Die Attach for Semiconductor Industry Forecast” looks at past sales and reviews total world Die Attach for Semiconductor sales in 2025, providing a comprehensive analysis by region and market sector of projected Die Attach for Semiconductor sales for 2026 through 2032. With Die Attach for Semiconductor sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Die Attach for Semiconductor industry.

This Insight Report provides a comprehensive analysis of the global Die Attach for Semiconductor landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Die Attach for Semiconductor portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Die Attach for Semiconductor market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Die Attach for Semiconductor and breaks down the forecast by Type, by Packaging, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Die Attach for Semiconductor.

This report presents a comprehensive overview, market shares, and growth opportunities of Die Attach for Semiconductor market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

Die Bonder

TCB Bonder

FC Die Bonder

Hybrid Bonder

Others

Segmentation by Application:

Logic

Memory

Optoelectronics

LED

Discrete

RF&MEMS

CIS

Segmentation by Packaging:

Advanced Packaging

Traditional Packaging

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

## APAC

China

Japan

Korea

Southeast Asia

India

Australia

## Europe

Germany

France

UK

Italy

Russia

## Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

HANMI Semiconductor

ASMPT

SEMES

Hanwha Semitech Co., Ltd

Yamaha Robotics (SHINKAWA)

Besi

Toray

Shibuya Corporation

Kulicke & Soffa

Fasford Technology

SUSS MicroTec

Palomar Technologies

Panasonic

Ultrasonic Engineering

Hesse GmbH

SET

Athlete FA

Finetech

Mycronic

Shenzhen Liande Automatic Equipment Co., Ltd

Guangdong Qrobot

Dalian Jafeng Automation Co.,Ltd

Capcon Limited

Easy Field Corporation

HiSOL,Inc

### Key Questions Addressed in this Report

What is the 10-year outlook for the global Die Attach for Semiconductor market?

What factors are driving Die Attach for Semiconductor market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Die Attach for Semiconductor market opportunities vary by end market size?

How does Die Attach for Semiconductor break out by Type, by Packaging?

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